



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

B.S. Beaman et al.

Serial No.: 09/251,988

Filed: February 17, 1999

For: Structural Design And Processes To Control Probe Position Accuracy
In A Wafer Test Probe Assembly

Assistant Commissioner for Patents
Washington, D.C. 20231

Date: July 5, 2001

Group Art Unit: 2858

Examiner: Jermele M. Hollington

Docket No.: YO999-088

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JUL 19 2001
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JUL 23 2001
JUL 26 2001
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AMENDMENT

Sir:

In response to Office Action dated January 19, 2001, please consider the following:

IN THE SPECIFICATION

Amend the paragraph bridging pages 7 and 8 as follows:

"Turning now to the figures, Figures 2 and 3 show two embodiments of the test assembly according to the present invention. Numerals common between Figures 2 and 3 represent the same thing. Probe head 40 is formed from a plurality of elongated electrically conducting members 42 embedded in a material 44 which is preferably an elastomeric material 44. The elongated conducting members 42 have ends 46 for probing contact locations on integrated circuit devices 48 of wafer 50. In the preferred embodiment, the workpiece is an integrated circuit such as a semiconductor chip or a semiconductor wafer having a plurality of chips. The workpiece can be any other electronic device. The opposite ends 52 of elongated electrical conductors 42 are in electrical contact with space transformer (or fan-out substrate) 54. In the preferred embodiment, space transformer 54 is a multilevel metal/ceramic substrate, a multilevel metal/polymer substrate or a printed circuit board which are typically used as packaging